

# SPECIFICATION FOR SMT OSCILLATOR MtronPTI P/N M2015S040

## **Electrical Specifications:**

Parameter	Symbol	Min.	Тур.	Max.	Units	Conditions
Frequency of Operation	Fo		1.000000		MHz	
		Fre	equency Sta	bility		
Frequency Stability	$\Delta F/F$	-100		+100	ppm	
			RF Outpu	t		
Output Type			HCMOS			
Output Load				50	pF	
Symmetry (duty cycle)	T <sub>DC</sub>	40	50	60	%	Ref to 1/2 VDD
Logic "1" Level	Vон	90% V <sub>DD</sub>			V	HCMOS load
Logic "0" Level	Vol			10% V <sub>DD</sub>	V	HCMOS load
Rise/Fall Time	T <sub>R</sub> /T <sub>F</sub>			7	nS	10% to 90% VDD HCMOS load
Tri-state Function		Logic "1" or floating				Lead1: Output Enabled
		Logic "0"				Lead1: Disables Output to Hi-Z
Supply Voltage & Power Consumption						
Operating Voltage	Vdd	4.5	5.0	5.5	V	
Operating Current IDD				20	mA	
Other Specifications						
Jitter (Cycle-to-Cycle)				20	ps	RMS

#### **Environmental & Mechanical Requirements:**

Operating Temperature	TA	-55		+125	°C	
Storage Temperature	Ts	-55		+125	°C	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, 1/2 sinewave)					
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
Hermeticity	Per MIL-STD-202, Method 112 (1 x 10 <sup>-8</sup> atm cc/s of Helium)					
Solderability	Per EIAJ-STD-002					
Max. Soldering Conditions	See solder profile, Figure 1					
Package Type	4 J-lead ceramic. Sn-Pb solder dipped leads.					
Screening	HiRel Screening required per Hamilton Product Specs.					



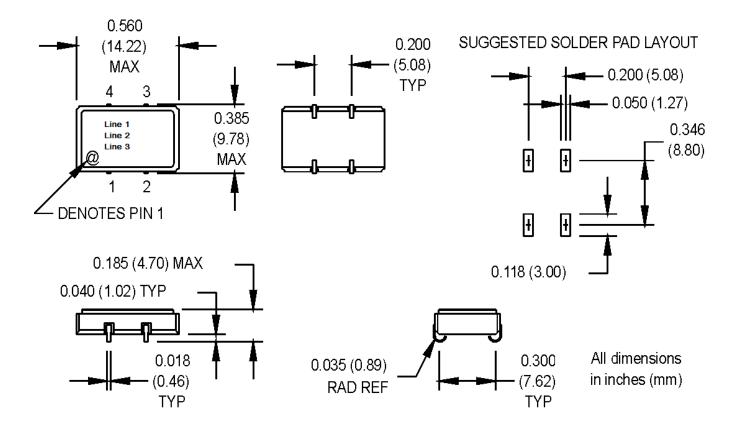
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### Dimensions, Marking, and Pin Out Information:

Pad	Function
1	Tri-state
2	Ground / Cover
3	Output
4	+V <sub>DD</sub>

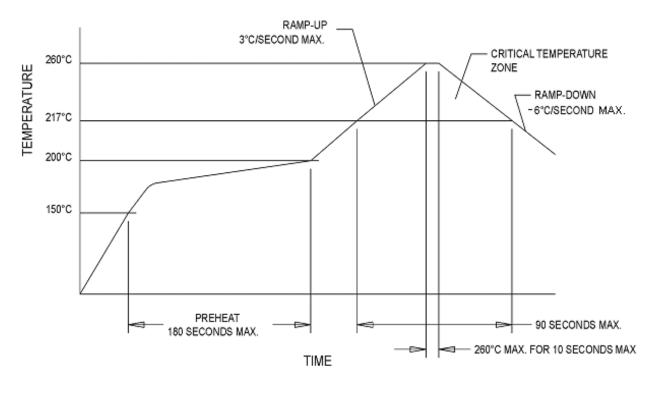
Part Marking		
Line 1	M2015S040	
Line 2	1.000000M	
Line 3	M-TRON yy ww	

Legend			
уу	Year		
ww	Work week		





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#### **Datasheet Revision Table:**

Date	Rev.	Author	Details of Revision
01/13/05	0	WNJ	Product Part Number changed to track product improvement. Product part number previously was 1517-006
01-13-05	A	WNJ	PCN 10065: Drop In Substrate mounting in the Ceramic package changed to a "sandwich" design to improve CTE issues in product testing and use in HiRel environments. Manual dispensing of epoxy changed to an automated process
02-18-08	В	WNJ	Datasheet updated to reflect Hamilton Specification update to Revision P – Rise and Fall time changed to 7ns from 10
09/14/17	С	MM	Datasheet format update